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"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Active
Core Processor	ARM® Cortex®-M4
Core Size	32-Bit Single-Core
Speed	72MHz
Connectivity	CANbus, EBI/EMI, I²C, IrDA, LINbus, SmartCard, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, LCD, POR, PWM, WDT
Number of I/O	95
Program Memory Size	2MB (2M x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	512K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.8V
Data Converters	A/D 16x12b SAR; D/A 2x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	120-VFBGA
Supplier Device Package	120-BGA (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/silicon-labs/efm32gg11b520f2048gl120-b

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4.1.6 Backup Supply Domain

Table 4.6. Backup Supply Domain

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Backup supply voltage range	V _{BU_VIN}		1.8	—	3.8	V
PWRRES resistor	R _{PWRRES}	EMU_BUCTRL_PWRRES = RES0	3400	3900	4400	Ω
		EMU_BUCTRL_PWRRES = RES1	1450	1800	2150	Ω
		EMU_BUCTRL_PWRRES = RES2	1000	1350	1700	Ω
		EMU_BUCTRL_PWRRES = RES3	525	815	1100	Ω
Output impedance between BU_VIN and BU_VOUT ²	R _{BU_VOUT}	EMU_BUCTRL_VOUTRES = STRONG	35	110	185	Ω
		EMU_BUCTRL_VOUTRES = MED	475	775	1075	Ω
		EMU_BUCTRL_VOUTRES = WEAK	5600	6500	7400	Ω
Supply current	I _{BU_VIN}	BU_VIN not powering backup domain	—	11	TBD	nA
		BU_VIN powering backup domain ¹	—	550	TBD	nA

Note:

1. Additional current required by backup circuitry when backup is active. Includes supply current of backup switches and backup regulator. Does not include supply current required for backed-up circuitry.
2. BU_VOUT and BU_STAT signals are not available in all package configurations. Check the device pinout for availability.

4.1.8 Wake Up Times

Table 4.10. Wake Up Times

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit	
Wake up time from EM1	t _{EM1_WU}		—	3	—	AHB Clocks	
Wake up from EM2	t _{EM2_WU}	Code execution from flash	—	11.8	—	μs	
		Code execution from RAM	—	4.1	—	μs	
Wake up from EM3	t _{EM3_WU}	Code execution from flash	—	11.8	—	μs	
		Code execution from RAM	—	4.1	—	μs	
Wake up from EM4H ¹	t _{EM4H_WU}	Executing from flash	—	94	—	μs	
Wake up from EM4S ¹	t _{EM4S_WU}	Executing from flash	—	294	—	μs	
Time from release of reset source to first instruction execution	t _{RESET}	Soft Pin Reset released	—	55	—	μs	
		Any other reset released	—	359	—	μs	
Power mode scaling time	t _{SCALE}	VSCALE0 to VSCALE2, HFCLK = 19 MHz ^{4 2}	—	31.8	—	μs	
		VSCALE2 to VSCALE0, HFCLK = 19 MHz ³	—	4.3	—	μs	
Note:							
1. Time from wake up request until first instruction is executed. Wakeup results in device reset.							
2. VSCALE0 to VSCALE2 voltage change transitions occur at a rate of 10 mV/μs for approximately 20 μs. During this transition, peak currents will be dependent on the value of the DECOUPLE output capacitor, from 35 mA (with a 1 μF capacitor) to 70 mA (with a 2.7 μF capacitor).							
3. Scaling down from VSCALE2 to VSCALE0 requires approximately 2.8 μs + 29 HFCLKs.							
4. Scaling up from VSCALE0 to VSCALE2 requires approximately 30.3 μs + 28 HFCLKs.							

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Supply current, continuous conversions, WARMUP-MODE=KEEPSENWARM	I_CSEN_ACTIVE	SAR or Delta Modulation conversions of 33 pF capacitor, CS0CG=0 (Gain = 10x), always on	—	90.5	—	µA
HFPERCLK supply current	I_CSEN_HFPERCLK	Current contribution from HFPERCLK when clock to CSEN block is enabled.	—	2.25	—	µA/MHz
Note:						
1. Current is specified with a total external capacitance of 33 pF per channel. Average current is dependent on how long the module is actively sampling channels within the scan period, and scales with the number of samples acquired. Supply current for a specific application can be estimated by multiplying the current per sample by the total number of samples per period (total_current = single_sample_current * (number_of_channels * accumulation)).						

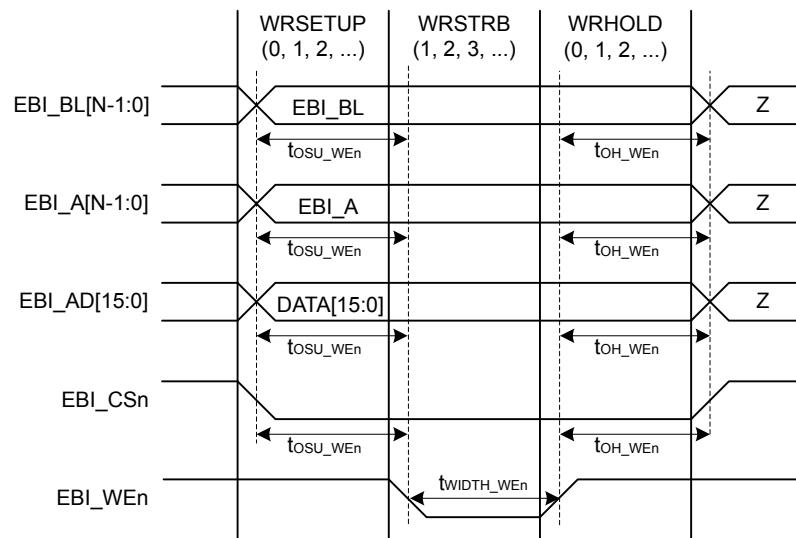


Figure 4.3. EBI Write Enable Output Timing Diagram

4.1.26 Ethernet (ETH)

MII Transmit Timing

Timing is specified with $3.0 \text{ V} \leq \text{IOVDD} \leq 3.8 \text{ V}$, 25 pF external loading, and slew rate for all GPIO set to 6 unless otherwise indicated.

Table 4.42. Ethernet MII Transmit Timing

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
TX_CLK frequency	$F_{\text{TX_CLK}}$	Output slew rate set to 7	—	25	—	MHz
TX_CLK duty cycle	$DC_{\text{TX_CLK}}$		35	—	65	%
Output delay, TX_CLK to TXD[3:0], TX_EN, TX_ER	t_{OUT}		0	—	25	ns

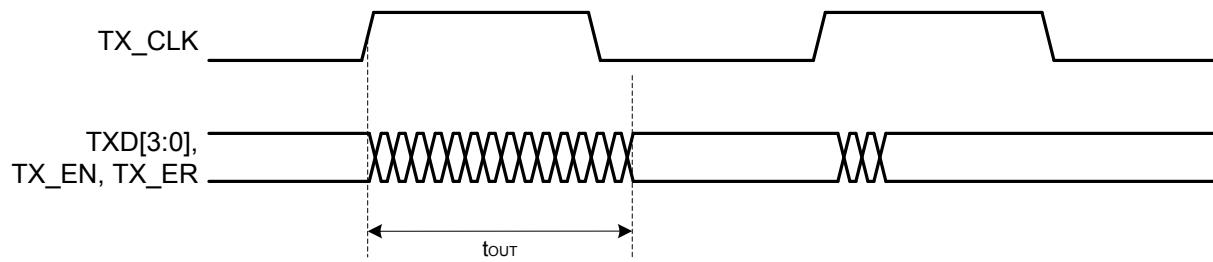


Figure 4.9. Ethernet MII Transmit Timing

Pin Name	Pin(s)	Description	Pin Name	Pin(s)	Description
PB2	M2	GPIO	PB3	M3	GPIO
PC6	M14	GPIO	VREGVSS	M15 N16	Voltage regulator VSS
VREGSW	M16	DCDC regulator switching node	PB4	N1	GPIO
PB5	N2	GPIO	PB6	N3	GPIO
PD5	N14	GPIO	PD4	N15	GPIO
PC0	P1	GPIO (5V)	PC1	P2	GPIO (5V)
PC2	P3	GPIO (5V)	PA8	P4	GPIO
PA11	P5	GPIO	PA13	P6	GPIO (5V)
PB9	P7	GPIO (5V)	PB12	P8	GPIO
PH2	P9	GPIO (5V)	PH5	P10	GPIO
PH8	P11	GPIO (5V)	PH11	P12	GPIO (5V)
PH13	P13	GPIO (5V)	PD0	P14	GPIO (5V)
PD3	P15	GPIO	PD8	P16	GPIO
PB7	R1	GPIO	PC3	R2	GPIO (5V)
PC5	R3	GPIO	PA9	R4	GPIO
BODEN	R5	Brown-Out Detector Enable. This pin may be left disconnected or tied to AVDD.	RESETn	R6	Reset input, active low. To apply an external reset source to this pin, it is required to only drive this pin low during reset, and let the internal pull-up ensure that reset is released.
PB10	R7	GPIO (5V)	PH0	R8	GPIO (5V)
PH3	R9	GPIO (5V)	PH6	R10	GPIO
PH9	R11	GPIO (5V)	PH12	R12	GPIO (5V)
PH14	R13	GPIO (5V)	PH15	R14	GPIO (5V)
PD2	R15	GPIO (5V)	PD7	R16	GPIO
PB8	T1	GPIO	PC4	T2	GPIO
PA7	T3	GPIO	PA10	T4	GPIO
PA12	T5	GPIO (5V)	PA14	T6	GPIO
PB11	T7	GPIO	PH1	T8	GPIO (5V)
PH4	T9	GPIO	PH7	T10	GPIO (5V)
PH10	T11	GPIO (5V)	PB13	T12	GPIO
PB14	T13	GPIO	AVDD	T14	Analog power supply.
PD1	T15	GPIO	PD6	T16	GPIO

Note:

1. GPIO with 5V tolerance are indicated by (5V).
2. The pins PD13, PD14, and PD15 will not be 5V tolerant on all future devices. In order to preserve upgrade options with full hardware compatibility, do not use these pins with 5V domains.

5.2 EFM32GG11B8xx in BGA152 Device Pinout

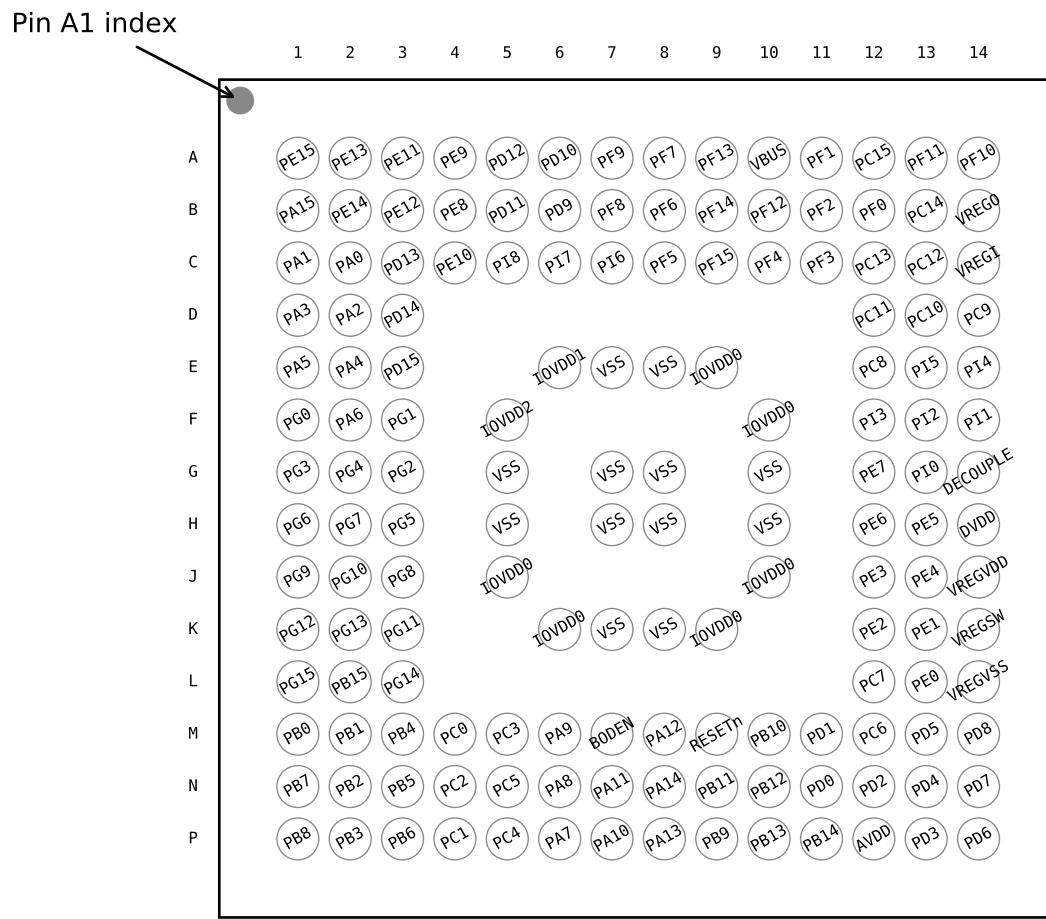


Figure 5.2. EFM32GG11B8xx in BGA152 Device Pinout

The following table provides package pin connections and general descriptions of pin functionality. For detailed information on the supported features for each GPIO pin, see [5.20 GPIO Functionality Table](#) or [5.21 Alternate Functionality Overview](#).

Table 5.2. EFM32GG11B8xx in BGA152 Device Pinout

Pin Name	Pin(s)	Description	Pin Name	Pin(s)	Description
PE15	A1	GPIO	PE13	A2	GPIO
PE11	A3	GPIO	PE9	A4	GPIO
PD12	A5	GPIO	PD10	A6	GPIO
PF9	A7	GPIO	PF7	A8	GPIO
PF13	A9	GPIO (5V)	VBUS	A10	USB VBUS signal and auxiliary input to 5 V regulator.
PF1	A11	GPIO (5V)	PC15	A12	GPIO (5V)
PF11	A13	GPIO (5V)	PF10	A14	GPIO (5V)

Pin Name	Pin(s)	Description	Pin Name	Pin(s)	Description
Note:					
1.	GPIO with 5V tolerance are indicated by (5V).				

Pin Name	Pin(s)	Description	Pin Name	Pin(s)	Description
PF11	A13	GPIO (5V)	PA15	B1	GPIO
PE13	B2	GPIO	PE11	B3	GPIO
PE8	B4	GPIO	PD12	B5	GPIO
PD10	B6	GPIO	PF8	B7	GPIO
PF6	B8	GPIO	PF13	B9	GPIO (5V)
PF4	B10	GPIO	PF3	B11	GPIO
NC	B12	No Connect.	PF10	B13	GPIO (5V)
PA1	C1	GPIO	PA0	C2	GPIO
PE10	C3	GPIO	PD13	C4	GPIO (5V)
VSS	C5 C8 H3 J3 K11 L12 L15	Ground	IOVDD1	C6	Digital IO power supply 1.
PF9	C7	GPIO	IOVDD0	C9 J11 K3 L11 L16	Digital IO power supply 0.
PF2	C10	GPIO	PF1	C11	GPIO (5V)
PC14	C12	GPIO (5V)	PC15	C13	GPIO (5V)
PA3	D1	GPIO	PA2	D2	GPIO
PB15	D3	GPIO (5V)	PF0	D11	GPIO (5V)
PC12	D12	GPIO (5V)	PC13	D13	GPIO (5V)
PA6	E1	GPIO	PA5	E2	GPIO
PA4	E3	GPIO	PC9	E11	GPIO (5V)
PC10	E12	GPIO (5V)	PC11	E13	GPIO (5V)
PB0	F1	GPIO	PB1	F2	GPIO
PB2	F3	GPIO	PE6	F11	GPIO
PE7	F12	GPIO	PC8	F13	GPIO (5V)
PB3	G1	GPIO	PB4	G2	GPIO
IOVDD2	G3	Digital IO power supply 2.	PE3	G11	GPIO
PE4	G12	GPIO	PE5	G13	GPIO
PB5	H1	GPIO	PB6	H2	GPIO
DVDD	H11	Digital power supply.	PE2	H12	GPIO
DECOPPLE	H13	Decouple output for on-chip voltage regulator. An external decoupling capacitor is required at this pin.	PD14	J1	GPIO (5V)
PD15	J2	GPIO (5V)	PE1	J12	GPIO (5V)
VREGVDD	J13	Voltage regulator VDD input	PC0	K1	GPIO (5V)

Pin Name	Pin(s)	Description	Pin Name	Pin(s)	Description
PC1	K2	GPIO (5V)	PE0	K12	GPIO (5V)
VREGSW	K13	DCDC regulator switching node	PC2	L1	GPIO (5V)
PC3	L2	GPIO (5V)	PA7	L3	GPIO
PB9	L13	GPIO (5V)	PB10	L14	GPIO (5V)
PD1	L17	GPIO	PC6	L18	GPIO
PC7	L19	GPIO	VREGVSS	L20	Voltage regulator VSS
PB7	M1	GPIO	PC4	M2	GPIO
PA8	M3	GPIO	PA10	M4	GPIO
PA13	M5	GPIO (5V)	PA14	M6	GPIO
RESETn	M7	Reset input, active low. To apply an external reset source to this pin, it is required to only drive this pin low during reset, and let the internal pull-up ensure that reset is released.	PB12	M8	GPIO
PD0	M9	GPIO (5V)	PD2	M10	GPIO (5V)
PD3	M11	GPIO	PD4	M12	GPIO
PD8	M13	GPIO	PB8	N1	GPIO
PC5	N2	GPIO	PA9	N3	GPIO
PA11	N4	GPIO	PA12	N5	GPIO (5V)
PB11	N6	GPIO	BODEN	N7	Brown-Out Detector Enable. This pin may be left disconnected or tied to AVDD.
PB13	N8	GPIO	PB14	N9	GPIO
AVDD	N10	Analog power supply.	PD5	N11	GPIO
PD6	N12	GPIO	PD7	N13	GPIO

Note:

1. GPIO with 5V tolerance are indicated by (5V).
2. The pins PD13, PD14, and PD15 will not be 5V tolerant on all future devices. In order to preserve upgrade options with full hardware compatibility, do not use these pins with 5V domains.

GPIO Name	Pin Alternate Functionality / Description				
	Analog	EBI	Timers	Communication	Other
PF7	BUSCY BUSDX LCD_SEG25	EBI_BL1 #0 EBI_BL1 #4 EBI_BL1 #5 EBI_DCLK #1	TIM0_CC1 #1 TIM4_CC1 #4	ETH_RMIITXD0 #1 US2_RX #4 QSPI0_CS0 #0 ETH_MIIRXER #2 US1_RX #3 U0_RX #0	PRS_CH23 #2
PF6	BUSDY BUSCX LCD_SEG24	EBI_BL0 #0 EBI_BL0 #4 EBI_BL0 #5 EBI_CSTFT #1	TIM0_CC0 #1 TIM4_CC0 #4 WTIM3_CC2 #5	ETH_RMIITXD1 #1 US2_TX #4 QSPI0_SCLK #0 US1_TX #3 U0_TX #0	PRS_CH22 #2
PI11				US4_RTS #3	
PI8		EBI_A13 #2	TIM1_CC2 #7 TIM4_CC0 #3	US4_CLK #3	
PF5	BUSCY BUSDX LCD_SEG3	EBI_REn #0 EBI_REn #5 EBI_A27 #1	TIM0_CDTI2 #2 TIM1_CC3 #6 TIM4_CC0 #2	US2_CS #5 I2C2_SCL #0 USB_VBUSEN	PRS_CH2 #1 DBG_TDI
PF13	BUSCY BUSDX		TIM1_CC0 #6 TIM4_CC0 #1 TIM5_CC1 #7 WTIM3_CC0 #7	US5_CLK #2 I2C2_SDA #4	
PF3	BUSCY BUSDX LCD_SEG1	EBI_ALE #0	TIM4_CC0 #0 TIM0_CDTI0 #2 TIM1_CC1 #5	CAN1_TX #1 US1_CTS #2 I2C2_SCL #5	CMU_CLK1 #4 PRS_CH0 #1 ETM_TD3 #1
PF2	BUSDY BUSCX LCD_SEG0	EBI_ARDY #0 EBI_A26 #1	TIM0_CC2 #4 TIM1_CC0 #5 TIM2_CC0 #3	US2_CLK #5 CAN0_TX #1 US1_TX #5 U0_RX #5 LEU0_TX #4 I2C1_SCL #4	CMU_CLK0 #4 PRS_CH0 #3 ACMP1_O #0 DBG_TDO DBG_SWO #0 GPIO_EM4WU4
PF1	BUSCY BUSDX	EBI_A25 #1	TIM0_CC1 #4 WTIM0_CC2 #4 LE- TIM0_OUT1 #2	US2_RX #5 CAN1_RX #1 US1_CS #2 U0_TX #5 LEU0_RX #3 I2C0_SCL #5	PRS_CH4 #2 DBG_SWDIOTMS GPIO_EM4WU3 BOOT_RX
PA1	BUSAY BUSBX LCD_SEG14	EBI_AD10 #0 EBI_DCLK #3	TIM0_CC0 #7 TIM0_CC1 #0 TIM3_CC1 #4 PCNT0_S1IN #4	ETH_RMIIRXD1 #0 ETH_MIITXD3 #0 SDIO_DAT1 #1 US3_RX #0 QSPI0_CS1 #1 I2C0_SCL #0	CMU_CLK1 #0 PRS_CH1 #0
PD12	LCD_SEG31	EBI_CS3 #0	TIM4_CC1 #6	ETH_RMIIRXER #1 SDIO_DAT4 #0 QSPI0_DQ3 #0 ETH_MIIRXCLK #2 US4_CS #1	
PD14		EBI_NANDWE #1	TIM2_CDTI1 #1 TIM3_CC2 #6 WTIM0_CC2 #1	ETH_MDC #1 CAN0_RX #5 US4_RTS #1 US5_CS #1 I2C0_SDA #3	

GPIO Name	Pin Alternate Functionality / Description				
	Analog	EBI	Timers	Communication	Other
PB0	BUSBY BUSAX LCD_SEG32	EBI_AD00 #1 EBI_CS0 #3 EBI_A16 #0	TIM2_CDTI0 #0 TIM1_CC0 #2 TIM3_CC2 #7 WTIMO_CC0 #5 PCNT0_S0IN #5 PCNT1_S1IN #2	LEU1_TX #3	PRS_CH4 #1 ACMP0_O #5
PE0	BUSDY BUSCX	EBI_A00 #2 EBI_A07 #0	TIM3_CC0 #1 WTIM1_CC1 #3 PCNT0_S0IN #1	CAN0_RX #6 U0_TX #1 I2C1_SDA #2	PRS_CH22 #1 ACMP2_O #1
PC7	BUSACMP0Y BU-SACMP0X OPA3_N	EBI_A06 #0 EBI_A13 #1 EBI_A21 #3	WTIM1_CC0 #3	US0_CTS #2 US1_RTS #3 LEU1_RX #0 I2C0_SCL #2	LES_CH7 PRS_CH15 #1 ETM_TD0 #2
PB1	BUSAY BUSBX LCD_SEG33	EBI_AD01 #1 EBI_CS1 #3 EBI_A17 #0	TIM2_CDTI1 #0 TIM1_CC1 #2 WTIM0_CC1 #5 LETIM1_OUT1 #5 PCNT0_S1IN #5	ETH_MIICRS #0 US5_RX #2 LEU1_RX #3	PRS_CH5 #1
PB2	BUSBY BUSAX LCD_SEG34	EBI_AD02 #1 EBI_CS2 #3 EBI_A18 #0	TIM2_CDTI2 #0 TIM1_CC2 #2 WTIM0_CC2 #5 LETIM1_OUT0 #5	ETH_MIICOL #0 US1_CS #6	PRS_CH18 #0 ACMP0_O #6
PB3	BUSAY BUSBX LCD_SEG20 / LCD_COM4	EBI_AD03 #1 EBI_CS3 #3 EBI_A19 #0	TIM1_CC3 #2 WTIM0_CC0 #6 PCNT1_S0IN #1	ETH_MIICRS #2 ETH_MDIO #0 SDIO_DAT6 #1 US2_TX #1 US3_TX #2 QSPI0_DQ4 #1	PRS_CH19 #0 ACMP0_O #7
PC6	BUSACMP0Y BU-SACMP0X OPA3_P	EBI_A05 #0	WTIM1_CC3 #2	US0_RTS #2 US1_CTS #3 LEU1_TX #0 I2C0_SDA #2	LES_CH6 PRS_CH14 #1 ETM_TCLK #2
PB4	BUSBY BUSAX LCD_SEG21 / LCD_COM5	EBI_AD04 #1 EBI_ARDY #3 EBI_A20 #0	WTIM0_CC1 #6 PCNT1_S1IN #1	ETH_MIICOL #2 ETH_MDC #0 SDIO_DAT7 #1 US2_RX #1 QSPI0_DQ5 #1 LEU1_TX #4	PRS_CH20 #0
PB5	BUSAY BUSBX LCD_SEG22 / LCD_COM6	EBI_AD05 #1 EBI_ALE #3 EBI_A21 #0	WTIM0_CC2 #6 LETIM1_OUT0 #4 PCNT0_S0IN #6	ETH_TSUEXTCLK #0 US0_RTS #4 US2_CLK #1 QSPI0_DQ6 #1 LEU1_RX #4	PRS_CH21 #0
PB6	BUSBY BUSAX LCD_SEG23 / LCD_COM7	EBI_AD06 #1 EBI_WEn #3 EBI_A22 #0	TIM0_CC0 #3 TIM2_CC0 #4 WTIM3_CC0 #6 LETIM1_OUT1 #4 PCNT0_S1IN #6	ETH_TSUTMRTOG #0 US0_CTS #4 US2_CS #1 QSPI0_DQ7 #1	PRS_CH12 #1
PD5	BUSADC0Y BU-SADC0X OPA2_OUT	EBI_A09 #1 EBI_A18 #3	TIM6_CC1 #7 WTIM0_CDTI1 #4 WTIM1_CC3 #1 WTIM2_CC2 #5	US1_RTS #1 U0_CTS #5 LEU0_RX #0 I2C1_SCL #3	PRS_CH11 #2 ETM_TD3 #0 ETM_TD3 #2

Alternate	LOCATION		
Functionality	0 - 3	4 - 7	Description
US3_RTS	0: PA5 1: PC1 2: PA14 3: PC15	4: PG5 5: PG11	USART3 Request To Send hardware flow control output.
US3_RX	0: PA1 1: PE7 2: PB7 3: PG7	4: PG1 5: PI13	USART3 Asynchronous Receive. USART3 Synchronous mode Master Input / Slave Output (MISO).
US3_TX	0: PA0 1: PE6 2: PB3 3: PG6	4: PG0 5: PI12	USART3 Asynchronous Transmit. Also used as receive input in half duplex communication. USART3 Synchronous mode Master Output / Slave Input (MOSI).
US4_CLK	0: PC4 1: PD11 2: PI2 3: PI8	4: PH6	USART4 clock input / output.
US4_CS	0: PC5 1: PD12 2: PI3 3: PI9	4: PH7	USART4 chip select input / output.
US4_CTS	0: PA7 1: PD13 2: PI4 3: PI10	4: PH8	USART4 Clear To Send hardware flow control input.
US4_RTS	0: PA8 1: PD14 2: PI5 3: PI11	4: PH9	USART4 Request To Send hardware flow control output.
US4_RX	0: PB8 1: PD10 2: PI1 3: PI7	4: PH5	USART4 Asynchronous Receive. USART4 Synchronous mode Master Input / Slave Output (MISO).
US4_TX	0: PB7 1: PD9 2: PI0 3: PI6	4: PH4	USART4 Asynchronous Transmit. Also used as receive input in half duplex communication. USART4 Synchronous mode Master Output / Slave Input (MOSI).
US5_CLK	0: PB11 1: PD13 2: PF13 3: PH12		USART5 clock input / output.
US5_CS	0: PB13 1: PD14 2: PF12 3: PH13		USART5 chip select input / output.
US5_CTS	0: PB14 1: PD15 2: PF11 3: PH14		USART5 Clear To Send hardware flow control input.
US5_RTS	0: PB12 1: PB15 2: PF10 3: PH15		USART5 Request To Send hardware flow control output.

Table 5.26. ACMP3 Bus and Pin Mapping

	APORT4Y	APORT4X	APORT3Y	APORT3X	APORT2Y	APORT2X	APORT1Y	APORT1X	APORT0Y	APORT0X	Port
BUSDY	BUSDX	BUSCY	BUSCX	BUSBY	BUSBX	BUSAY	BUSAX	BUSACMP3Y	BUSACMP3X	BUS	CH31
PF15	PF15			PB15		PB15					CH30
PF14		PF14		PB14			PB14				CH29
PF13	PF13			PB13	PB13		PB12				CH28
PF12		PF12		PB12		PB11	PB11				CH27
PF10	PF11	PF11		PB10		PB10	PB10				CH26
PF8		PF9	PF9		PB9	PB9	PB9				CH25
PF7	PF7		PF8								CH24
PF6	PF5	PF5	PF6	PB6	PB6	PB5	PB5	PB6			CH23
PF4		PF4	PF4	PB4	PB4	PB3	PB3	PB4			CH22
PF2	PF1	PF1	PF2	PB2	PB2	PB1	PB1	PB2			CH21
PF0		PF3	PF3	PB0	PB0	PB0	PB0	PB0			CH20
PE15	PE15		PE15	PE15		PA15	PA15	PA14			CH19
PE14		PE13	PE13	PE14	PE14	PA13	PA13	PA14			CH18
PE12		PE11	PE11	PE12	PE12	PA12	PA12	PA12			CH17
PE10		PE10		PE10	PE10	PA11	PA11	PA11			CH16
PE8		PE9	PE9	PE8	PE8	PA9	PA9	PA9			CH15
PE6		PE7	PE7	PE6	PE6	PA8	PA8	PA8			CH14
PE5		PE5		PE5		PA7	PA7	PA7			CH13
PE4			PE4		PE4	PA5	PA5	PA6	PA6	PA6	CH12
					PA4	PA4	PA4	PA4	PA4	PA4	CH11
					PA3	PA3	PA3	PA3	PA3	PA3	CH10
PE1		PE1		PE1		PA2	PA2	PA2	PA2	PA2	PA2
PE0			PE0	PE0	PE0	PA1	PA1	PA1	PA1	PA1	PA1

Table 5.31. VDAC0 / OPA Bus and Pin Mapping

OPA3_OUT		OPA3_P		VDAC0_OUT0 / OPA0_OUT		OPA3_IN		OPA3_IN		OPA3_IN	
APORT4Y	APORT3Y	APORT2Y	APORT1Y	APORT4X	APORT3X	APORT2X	APORT1X	APORT4Y	APORT3Y	APORT2Y	APORT1Y
BUSDY	BUSCY	BUSBY	BUSAY	BUSDX	BUSCX	BUSEBX	BUSAIX	BUSDY	BUSCY	BUSBY	BUSAY
PF15		PF15		PF15		PF15		PF15		PF15	
PF14		PF14		PF14		PF14		PF14		PF14	
PF13		PF13		PF13		PF13		PF13		PF13	
PF12		PF12		PF12		PF12		PF12		PF12	
PF11		PF11		PF11		PF11		PF11		PF11	
PF10		PF10		PF10		PF10		PF10		PF10	
PF9		PF9		PF9		PF9		PF9		PF9	
PF8		PF8		PF8		PF8		PF8		PF8	
PF7		PF7		PF7		PF7		PF7		PF7	
PF6		PF6		PF6		PF6		PF6		PF6	
PF5		PF5		PF5		PF5		PF5		PF5	
PF4		PF4		PF4		PF4		PF4		PF4	
PF3		PF3		PF3		PF3		PF3		PF3	
PF2		PF2		PF2		PF2		PF2		PF2	
PF1		PF1		PF1		PF1		PF1		PF1	
PF0		PF0		PF0		PF0		PF0		PF0	
PE15		PE15		PE15		PE15		PE15		PE15	
PE14		PE14		PE14		PE14		PE14		PE14	
PE13		PE13		PE13		PE13		PE13		PE13	
PE12		PE12		PE12		PE12		PE12		PE12	
PE11		PE11		PE11		PE11		PE11		PE11	
PE10		PE10		PE10		PE10		PE10		PE10	
PE9		PE9		PE9		PE9		PE9		PE9	
PE8		PE8		PE8		PE8		PE8		PE8	
PE7		PE7		PE7		PE7		PE7		PE7	
PE6		PE6		PE6		PE6		PE6		PE6	
PE5		PE5		PE5		PE5		PE5		PE5	
PE4		PE4		PE4		PE4		PE4		PE4	
		PA3				PA3				PA3	
		PA2				PA2				PA2	
		PA1				PA1				PA1	
		PA0				PA0				PA0	

Table 6.2. BGA192 PCB Land Pattern Dimensions

Dimension	Min	Nom	Max
X		0.20	
C1		6.00	
C2		6.00	
E1		0.4	
E2		0.4	

Note:

1. All dimensions shown are in millimeters (mm) unless otherwise noted.
2. Dimensioning and Tolerancing is per the ANSI Y14.5M-1994 specification.
3. This Land Pattern Design is based on the IPC-7351 guidelines.
4. All metal pads are to be non-solder mask defined (NSMD). Clearance between the solder mask and the metal pad is to be 60 µm minimum, all the way around the pad.
5. A stainless steel, laser-cut and electro-polished stencil with trapezoidal walls should be used to assure good solder paste release.
6. The stencil thickness should be 0.125 mm (5 mils).
7. The ratio of stencil aperture to land pad size should be 1:1.
8. A No-Clean, Type-3 solder paste is recommended.
9. The recommended card reflow profile is per the JEDEC/IPC J-STD-020C specification for Small Body Components.

6.3 BGA192 Package Marking



Figure 6.3. BGA192 Package Marking

The package marking consists of:

- PPPPPPPPPP – The part number designation.
- TTTTTT – A trace or manufacturing code. The first letter is the device revision.
- YY – The last 2 digits of the assembly year.
- WW – The 2-digit workweek when the device was assembled.

Table 7.1. BGA152 Package Dimensions

Dimension	Min	Typ	Max
A	0.78	0.84	0.90
A1	0.13	0.18	0.23
A3	0.16	0.20	0.24
A2		0.45 REF	
D		8.00 BSC	
e		0.50 BSC	
E		8.00 BSC	
D1		6.50 BSC	
E1		6.50 BSC	
b	0.20	0.25	0.30
aaa		0.10	
bbb		0.10	
ddd		0.08	
eee		0.15	
fff		0.05	

Note:

1. All dimensions shown are in millimeters (mm) unless otherwise noted.
2. Dimensioning and Tolerancing per ANSI Y14.5M-1994.
3. Recommended card reflow profile is per the JEDEC/IPC J-STD-020 specification for Small Body Components.